TopLine's Martin Hart to Present "Reliability of Cu-Wrap and Braided Column CGAs for Extreme Cold Applications" at Upcoming Pan Pacific Symposium

Milledgeville, GA, USA - **Martin Hart,** CEO of TopLine Corporation, will present "Reliability of Cu-Wrap and Braided Column CGAs for Extreme Cold Applications" at the upcoming Pan Pacific Strategic Electronics Symposium, February 2-5, 2026, at The Hapuna Westin Resort, Big Island, Hawaii, USA.

Hart is presenting a technical paper that is co-authored with Reza Ghaffarian of JPL NASA. This paper documents the findings of the accelerated thermal cycle testing done on TopLine braided columns. The topic addresses column reliability in extremely cold environments.

cording to Hart, "Braided Solder Columns can withstand the rigors of deep space cold and cryogenic environments and represent a robust new solution to challenges facing next generation large packages in electronics assembly."

For more information, visit https://smta.org/mpage/panpac-program/. Hart adds that this is the first event to kick off 2026 wherein this information is being publicly presented. For more information about TopLine, contact TopLine Corporation at 95 HWY. 22 W., Milledgeville, GA 31061 USA Telephone: 800-776-9888, Email: info@topline.tv.

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About TopLine

TopLine manufactures a wide range of solder columns for CCGA semiconductor packages, and provides Daisy Chain CCGA packages for engineering development, profiling and practice. TopLine products provide hands-on learning for engineers. TopLine is a pioneer in CGA solder columns technology and low temperature cryogenic package-to-board interconnects. TopLine is also a supplier of bonding wire for many semiconductor uses and for EV applications. To learn more, visit www.CCGA.tv or call (1+) 800 – 776-9888.

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